
Foreword

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Biographical notes: Cemal Basaran is a Professor and the Director of Electronic Packaging Laboratory at the State University of New York at Buffalo. He specialises in experimental and computational damage mechanics of power and nanoelectronics packaging. He has authored more than 140 publications in the field of thermodynamics-based damage mechanics of electronics packaging under electromigration, thermomigration and thermo-mechanical loads and high sensitivity, nanoscale, moiré interferometry inspection. He received a MS in Civil Engineering from MIT and a PhD in Engineering Mechanics from the University of Arizona in Tucson. He is 1997 Recipient of the ONR Young Investigator Award.

Hua Ye is a Research Scientist at College of Nanoscale Science and Engineering, State University of New York at Albany. His research interests include micro and nanoelectronic packaging, novel power semiconductor device and solar cell designing, modelling and processing. He has published more than 40 technical papers on these subjects. He is a Member of IEEE and IMAPS. He was the Recipient of 2001–2002 IMAPS Educational Grant. He received both a BS and MS from Tongji University, China and a PhD from State University of New York at Buffalo.

We would like to thank the *IJMPT* Editors for inviting us to guest edit this Special Issue on Micro/Nanoelectronics and NEMS and MEMS Packaging. Putting together Special Issues of journals is usually time-consuming and challenging. This particular project, however, has been well worth the time. Developments in the electronics and electromechanical systems fields have been taking place at a head-spinning pace. Accordingly, we have invited the world's leading researchers in these fields to collaborate in order to assemble this special edition. We expect that this monograph will be very helpful to the researchers and engineers already working in these fields, as well as those who are trying to get into them. The contributions assembled in this issue range from very theoretical papers that hypothesise the improbability of monople

electronic devices to very application-oriented implementations of algorithms for size effect in small scale structures. This Special Issue would not have been possible without the great help we received from the authors. We are grateful for all the help they have given us.